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General Requirements for Dielectric Surface Mounting Adhesives

Supersedes IPC-SM-817

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A standard developed by IPC

Association Connecting Electronics Industries



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- Show relationship to Design for Manufacturability (DFM) and Design for the Environment (DFE)
- Minimize time to market
- Contain simple (simplified) language
- Just include spec information
- Focus on end product performance
- Include a feedback system on use and problems for future improvement

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- Increase time-to-market
- Keep people out
- Increase cycle time
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Developed by the IPC-SM-817 Task Group (5-21k) of the Assembly and Joining Committee (5-20) of IPC

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Users of this publication are encouraged to participate in the development of future revisions.

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Table of Contents

1 SCOPE	1	4.1.2 Test Equipment and Inspection Facilities	5
1.1 Purpose	1	4.2 Classification of Inspections	5
1.2 Adhesive Classification	1	4.3 Qualification Inspection	5
1.2.1 Adhesive Cure System	1	4.3.1 Sample Size	5
2 APPLICABLE DOCUMENTS	1	4.3.2 Inspection Routine	5
2.1 IPC	1	4.3.3 Failures	5
2.2 ASTM	1	4.3.4 Modification of Qualified Products	6
2.3 Department of Defense	2	4.4 Quality Conformance Inspection	6
3 REQUIREMENTS	2	4.4.1 Inspection of Product for Delivery	6
3.1 Terms and Definitions	2	4.4.2 Inspection of Packaging	6
3.2 General Requirements	3	4.4.3 Reporting of Results	7
3.2.1 Workmanship	3	4.5 Test Procedures	7
3.2.2 General Design Considerations	3	4.5.1 Degree of Fineness	7
3.2.3 Compatibility	3	4.5.2 Viscosity	7
3.2.4 Shelf Life	3	4.5.3 Shear Strength	7
3.2.5 Degree of Fineness	3	4.5.4 Spread/Slump	7
3.2.6 Color & Opacity	4	4.5.5 Resistance to Solvents	7
3.3 Physical Requirements	4	4.5.6 Dielectric Strength	7
3.3.1 Viscosity	4	4.5.7 Dielectric Constant	7
3.3.2 Working Time	4	4.5.8 Dissipation Factor	7
3.3.3 Spread/Slump	4	4.5.9 Volume Resistivity	7
3.3.4 Shear Strength	4	4.5.10 Surface Resistivity	7
3.4 Chemical Requirements	4	4.5.11 Moisture and Insulation Resistance	7
3.4.1 Cure	4	4.5.12 High Temperature	8
3.4.2 Resistance To Solvents	4	4.5.13 Fungus Resistance	8
3.4.3 Hydrolytic Stability/Aging	4	4.5.14 Hydrolytic Stability	8
3.5 Electrical Testing	4	4.5.15 Electrochemical Migration	8
3.5.1 Dielectric Strength	4	4.5.16 Outgassing	8
3.5.2 Dielectric Constant	4	5 NOTES	8
3.5.3 Dissipation Factor	4	5.1 Ordering Data	8
3.5.4 Volume Resistivity	4	5.2 Intended Use	8
3.5.5 Surface Resistivity	4	5.3 Marking And Labeling	8
3.6 Environmental Requirements	4	5.4 Safety	8
3.6.1 Moisture and Insulation Resistance	4	5.5 Waste Disposal	8
3.6.2 High Temperature Strength	4	5.6 Packaging Material	8
3.6.3 Fungus Resistance	4	5.7 Storage	8
3.6.4 Electrochemical Migration	5	5.8 Chip Torsional Strength	8
3.6.5 Outgassing	5		
4 QUALITY ASSURANCE PROVISIONS	5		
4.1 Responsibility for Inspection	5		
4.1.1 Responsibility for Compliance	5		

Figures

Figure 3-1 Fillet, Adhesive 2

Tables

Table 4-1 Qualification Inspection 6

Table 4-2 Group A Inspections 6

Table 4-3 Test Solvents 7